



PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Mostafazadeh et al.

Attorney Docket No.: NSC1P217D2/NS-3877-2

Application No.: 09/625,071

Examiner: Clark, S.

Filed: July 25, 2000

Group: 2815

Title: LEAD FRAME CHIP SCALE PACKAGE

Pre Amdt  
13/D  
10-18-01  
J. Flanagan

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, Washington, DC 20231 on September 24, 2001.

Signed:

Lara M. Nelson  
Lara M. Nelson

**AMENDMENT ACCOMPANYING RCE**

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

Please enter the following amendments and remarks when Examining this RCE.

**IN THE CLAIMS**

Please replace the existing claim set with the following revised claim set, which includes a number of new claims (i.e., claims 18-44). A marked up version of the amended claims illustrating the changes made is provided as an Appendix to this response.

11. (Twice Amended) A lead frame panel suitable for forming an array of integrated circuit packages for accommodating a semiconductor die, the lead frame panel having an array of device areas, each device area being suitable for forming an independent integrated circuit package and comprising:

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